ABOCIATION CONNECTING LECTRONICS INDUSTRIES® INTERNAL MAterial Composition © Copyright 2005. IPC, Bar international and Pan-Amer	nnockburn, Illinois, A	ll rights reserved untions.	Inder both This doc level par	ament is a decl s, the declaration	aration of th on encomp	he substances asses all lowe	s within the manufacture er level materials for w	rer listed ite hich the ma	m. Note: if nufacturer	the item is an as has engineering	sembly with lower responsibility.	
	21.1 IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute			Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information								
Supplier Information												
mpany name* Company unique ID		que ID	D U		Unique ID Authority				Response Date*			
onsemi	ni							2024-05-10				
Contact Name	Title - Contac	et		Phone - Contact*				Email - Contact*				
Product-Env-Stewards	Product Envi		NA				Product-Env-Stewards@onsemi.com					
thorized Representative* Title - Representative				Phone - Representative*				Email - Representative*				
Product-Env-Stewards	iro Compliance		NA	NA			Product-Env-Stewards@onsemi.com					
Requester Item Number M	fr Item Number	Mfr Item Name		Effective I	Date Vers	sion	Manufacturing Site	W	eight*	UOM	Unit Type	
	CV8154MW300300 Dual 300 mA, Lov 3G		w IQ, LDO, wettable fla	ıks 2024-05-1	2024-05-10 MY1		MY1	23.85		mg	Each	
Manufacturing Proccess Information												
Terminal Plating / Grid Array Material	1 Terminal Base Alloy J		J-STD-020 MSL Rating	Peak	Process Body Temperature Max Time at Peak		Temperatu	e Numbe	er of Reflow Cyc	les		
Matte Tin (Sn) - annealed CU Alloy 1		1	260		С	30	second	3				
Comments												
level 1 - maximum time at peak temperature dur	ing soldering is 10-3	0 seconds										
For more information regarding material compo	sition please refer to	page 3										

RoHS Material Composition Declaration				Declaration Type *	Detailed
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		nium (Cr6+), Polybro	ominated Biphenyls (PBB), Polybron	dmium and quantity limit of 0.1% by mass (100 minated Diphenyl Ethers (PBDE), and Bis(2-eth	
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe v others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	on above	Supplier Acceptance	* Accepted	
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all
Exemption List Version	EL-2011/534/EU				
Declaration Signature					
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the
Supplier Digital Signature Ra	stislav Drska	Le			

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	1.01	mg	Supplier	Silicon (Si)	7440-21-3		1.01	mg
Die Attach	0.12	mg	Supplier	Isobornyl Methacrylate	7534-94-3		0.0072	mg
			Supplier	Silver (Ag)	7440-22-4		0.0978	mg
			Supplier	Isobornyl Acrylate	5888-33-5		0.0072	mg
			Supplier	Misc.	Proprietary Data		0.0006	mg
			Supplier	Tricyclo[5.2.1.02,6]decanedimethanol Diacrylate (C18H24O4)	42594-17-2		0.0072	mg
Lead Frame 7.	7.06	mg	Supplier	Tin (Sn)	7440-31-5		0.0176	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0155	mg
			Supplier	Chromium (Cr)	7440-47-3		0.0176	mg
			Supplier	Copper (Cu)	7440-50-8		7.0092	mg
ead Frame plating	0.14	mg	Supplier	Silver (Ag)	7440-22-4		0.14	mg
Mold Compound-Black	14.2	mg		Epoxy resin	proprietary data		0.6674	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		1.42	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0142	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		11.431	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.6674	mg
Plating	1.1	mg	Supplier	Tin (Sn)	7440-31-5		1.1	mg
Wire Bond - Au	0.22	mg	Supplier	Gold (Au)	7440-57-5		0.22	mg